12-AUG-2005 Rev B

COMPACT FLASH CARD, 1.27mm(.050") PITCH

1. INTRODUCTION

1.1. Purpose

Testing was performed on the Tyco COMPACT FLASH CARD, 1.27mm(.050") **PITCH** to determine its conformance to the requirements of Product Specification 108-57134 Revision B.

1.2. Scope

This report covers the electrical, mechanical, and environmental performance of the COMPACT FLASH CARD, 1.27mm(.050").

1.3. Conclusion

The COMPACT FLASH CARD, 1.27mm(.050") Connector meets the electrical, mechanical, and environmental performance requirements of Product Specification 108-57134 Revision B.

1.4. Product Description

The COMPACT FLASH CARD, 1.27mm(.050") Connector is designed for printed circuit board applications. The contacts are copper alloy, Gold plated on the contact interface and Tin plating on the soldertail, all over nickel under-plated. The housing material is glass filled insulating polymer, UL94V-0.

1.5. Test samples

The test samples were randomly selected from normal current production lots, and the following part numbers were used for test:

Test Group	Quantity	Description
A, B, C, D, E, F, G, H, I,	5EA.	COMPACT FLASH CARD, 1.27mm(.050")

DR	DATE	APVD	DATE
Oblic Hu	12-Aug-2005	Wei-Jei Ke	12-Aug-2005
			P-05-000084

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1.6. QUALIFICATION TEST SEQUENCE

Test Group									
Test or Examination	Α	В	O	D	Е	F	G	Ι	I
	Test Sequence (a)								
Examination of Product	1, 7	1, 9	1, 6	1, 5	1, 5	1, 5	1, 5	1, 3	1, 3
Contact Resistance		2, 8	2, 5	2, 4	2, 4	2, 4	2, 4		
Dielectric withstanding Voltage	3, 6								
Insulation Resistance	2, 5								
Mating Force		3, 7							
Unmating Force		4, 6							
Durability		5							
Vibration			3						
Mechanical Shock			4						
Contact Retention Force								4	
Solderability									2
Resistance to Soldering Heat								2	
Thermal Shock				3					
Humidity Temperature Cycling	4				3				
Temperature Life						3			
Salt Spray							3		

Figure 1.
NOTE: (a) Numbers indicate sequence in which tests are performed.

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2. TEST RESULT

GP	TEST	SDEC	DATA					
GP	IESI	SPEC.	Max.	Min.	Mean	σ		
	Insulation Resistance	1000 MΩMin.	ОК	ОК	ОК			
Α	Dielectric withstanding Voltage	500 VAC 1Minute	ОК	ОК	ОК			
	Humidity Temperature Cycling	25-65°C,95%,10cycle	ОК	ОК	ОК			
	Insulation Resistance	1000 MΩ Min.	ОК	ОК	ОК			
	Dielectric withstanding Voltage	500 VAC 1Minute	ОК	ОК	ОК			
	Appearance	No Damaged	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	28.58 m Ω	26.24m Ω	27.46m $Ω$			
	Mating Force	2.94 kgf Max	1.28kg	1.12kg	1.16kg			
	Unmating Force	0.5 kgf Min	1.11kg	0.972kg	1.52kg			
	Durability	1000 Cycle	2.26kg	1.01kg	1.64kg			
В	Unmating Force	0.5 kgf Min	2.31kg	2.18kg	2.22kg			
	Mating Force	2.94 kgf Max	2.48kg	2.22kg	2.34kg			
	Contact Resistance	40 m Ω Max.	28.82m Ω	26.68m Ω	27.74m $Ω$			
	Appearance	No Damaged	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	28.56 m Ω	26.60m Ω	27.42m $Ω$			
	Vibration	10-55-10 Hz	ОК	ОК	ОК			
С	Mechanical Shock	50G, 11mSec	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	28.64 m Ω	26.83 m Ω	27.76m $Ω$			
	Appearance	No Damaged	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	28.72 m Ω	26.41m Ω	27.42m $Ω$			
D	Thermal Shock	-55°C, +85°C 5 Cycle	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	29.61m Ω	27.15m $Ω$	28.67 m Ω			
	Appearance	No Damaged	ОК	ОК	ОК	-		
	Contact Resistance	40 m Ω Max.	28.18mΩ	26.36m Ω	27.37mΩ	-		
_	Humidity Temperature Cycling	25-65°C, 95%, 10cycle	ОК	ОК	ОК	-		
E	Contact Resistance	40 m Ω Max.	32.64 m Ω	27.48m Ω	28.43 m Ω	-		
	Appearance	No Damaged	ОК	ОК	ОК	-		

Figure 2 (Con.)

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GP	TEST	SPEC.	DATA					
GP	IESI	SPEC.	Max.	Min.	Mean	σ		
	Contact Resistance	40 m Ω Max.	28.53 m Ω	26.48m Ω	27.52 m Ω			
l _F	Temperature Life	85℃ 250Hr	ОК	ОК	ОК			
「	Contact Resistance	40 m Ω Max.	29.58m Ω	26.87 m Ω	28.72 m Ω			
	Appearance	No Damaged	ОК	ОК	ОК			
	Contact Resistance	40 m Ω Max.	28.67 m Ω	26.16m Ω	27.32mΩ			
	Salt Spray	35℃, 5%Salt, 48hours	ОК	ОК	ОК			
G	Contact Resistance	40 m Ω Max.	31.68m Ω	28.74 m Ω	29.62m Ω			
	Appearance	No Damaged	ОК	ОК	ОК			
	Resistance to Solder Heat	No Damaged	ОК	ОК	OK			
Н	Appearance	No Damaged	ОК	ОК	ОК			
	Contact Retention Force	1kg MIN.	2.0kg	2.0kg	2.0Kg			
	Solderbility	235°C, 5sec	ОК	ОК	ОК			
'	Appearance	No Damaged	ОК	ОК	OK			

Figure 2 (End)

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